

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		10/785,122	HALL ET AL.	
		Examiner	Art Unit	Page 1 of 1
		José R. Díaz	2815	

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,719,440	02-1998	Moden, Walter L.	257/697
	B	US-6,359,334 B1	03-2002	Jiang, Tongbi	257/706
	C	US-5,585,600 A	12-1996	Froebel et al.	174/52.4
	D	US-5,548,160 A	08-1996	Corbett et al.	257/666
	E	US-5,840,598 A	11-1998	Grigg et al.	438/118
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Tummala et al., Microelectronics Packaging Handbook Semiconductor Packaging Part II, Chapman and Hall, 2 <sup>nd</sup> Ed., 1997, pages 25-26, 42-44, 91-93, 887-890.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.